

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	[METAL BONDING METHOD FOR SEMICONDUCTOR CIRCUIT COMPONENTS EMPLOYING PRESCRIBED FEEDS OF METAL BALLS]		
Application Number :			
Date :			
First Named Applicant:	Mr. Cheng-Chieh Yang		
Attorney Docket Number:	11053-US-PA		
TOTAL FEE AUTHORIZED \$ 385			
Patent fees are subject to annual revisions on or about October 1st of each year.			
Filing as small entity			
BASIC FILING FEE			
Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	2001	385	385
Subtotal For Basic Filing Fees: \$ 385			
EXTRA CLAIM FEES			
Fee Description	Extra Claim	Fee Code	Amount \$
Total Claims : 10	0	2202	9
Independent Claims : 1	0	2201	43
Subtotal For Extra Claims Fees: \$ 0			
AUTHORIZED BILLING INFORMATION			
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:			
Credit account number:	1000		
Expiration Date (YYYYMMDD):	2006-10-31		
Authorized name:	LEE, HUAI-LU		
Billing address:	99999		